

## **STTH8S06**

#### Turbo 2 ultrafast high voltage rectifier

#### **Features**

- Ultrafast recovery
- Low reverse recovery current
- Reduces losses in diode and switching transistor
- Low thermal resistance
- Higher frequency operation
- Insulated TO-220FPAC version
  - Insulation voltage = 1500 V rms
  - Package capacitance = 12 pF

#### **Description**

ST's STTH8S06 is a state of the art ultrafast recovery diode. By the use of 600 V Pt doping planar technology, this diode will out-perform the power factor corrections circuits operating in hardswitching conditions. The extremely low reverse recovery current of the STTH8S06, reduces significantly the switching power losses of the MOSFET and thus increases the efficiency of the application. This leads designers to reduce the size of their heatsinks.

This device is also intended for applications in power supplies and power conversions systems, motor drive, and other power switching applications.

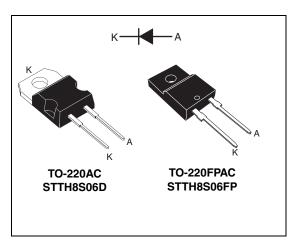


Table 1. Device summary

,			
I <sub>F(AV)</sub>	8 A		
$V_{RRM}$	600 V		
I <sub>RM</sub> (typ.)	4.4 A		
T <sub>j</sub> (max)	175 °C		
V <sub>F</sub> (typ)	1.5 V		
t <sub>rr</sub> (typ)	12 ns		

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## 1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	600	V
I <sub>F(AV)</sub>	Average forward current	8	Α
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ ms}$	60	Α
T <sub>stg</sub>	Storage temperature range	-65 to + 175	°C
Tj	Maximum operating junction temperature	175	°C

Table 3. Thermal parameter

Symbol	Parameter	Parameter I		
р.	lunction to case	TO-220AC	3.0	°C/W
R <sub>th(j-c)</sub> Junction to case		TO220FPAC	5.5	C/VV

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур	Max.	Unit
	Reverse leakage current	T <sub>j</sub> = 25 °C	V 600 V			20	
<sup>I</sup> R	T <sub>j</sub> = 125 °C $^{\text{V}_{\text{R}}}$ = 000 V	e current $T_{j}=125 ^{\circ}\text{C}$ $V_{R}=600 ^{\circ}\text{V}$		25	200	μΑ	
V	V <sub>F</sub> Forward voltage drop		I <sub>F</sub> = 8 A			3.4	V
VF	Tronward voltage drop	T <sub>j</sub> = 125 °C	IF - O A		1.5	1.9	V

To evaluate the maximum conduction losses use the following equation: P = 1.20 x  $I_{F(AV)}$  + 0.087  $I_{F}^{2}_{(RMS)}$ 

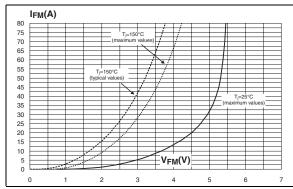
Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур	Max.	Unit
t <sub>rr</sub>	Reverse recovery time	$I_F = 1 \text{ A}, dI_F/dt = -200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			12	18	ns
I <sub>RM</sub>	Reverse current				1.6	2.2	Α
S <sub>factor</sub>	Softness factor	T <sub>j</sub> = 25 °C	$I_F = 8 \text{ A}, dI_F/dt = -200 \text{ A/}\mu\text{s},$ $V_R = 200 \text{ V}$		1		-
Q <sub>rr</sub>	Reverse recovery charges				17		nC
I <sub>RM</sub>	Reverse current		I <sub>F</sub> = 8 A, dI <sub>F</sub> /dt = - 200 A/μs, V <sub>R</sub> = 200 V		4.4	6.0	Α
S <sub>factor</sub>	Softness factor	T <sub>j</sub> = 125 °C			0.3		-
Q <sub>rr</sub>	Reverse recovery charges		n		90		nC

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Figure 1. Forward voltage drop versus forward current

Figure 2. Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC)



Zth(j-c)/Rth(j-c)

1.0

0.9

0.8

0.7

0.6

0.5

0.4

0.3

0.2

Single pulse

0.1

1.E-03

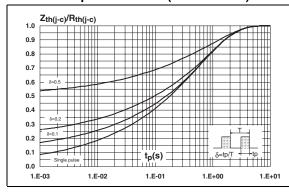
1.E-02

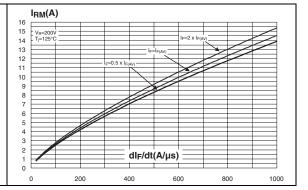
1.E-01

1.E+00

Figure 3. Relative variation of thermal impedance junction to case versus pulse duration(TO-220FPAC)

Figure 4. Peak reverse recovery current versus dl<sub>F</sub>/dt (typical values)





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Figure 5. Reverse recovery time versus  $d_F/dt$  Figure 6. Reverse recovery charges versus  $d_F/dt$  (typical values)

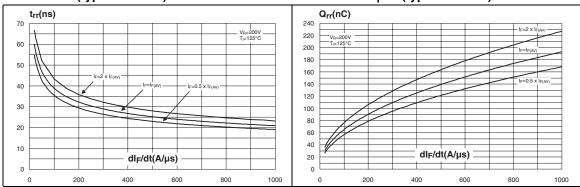
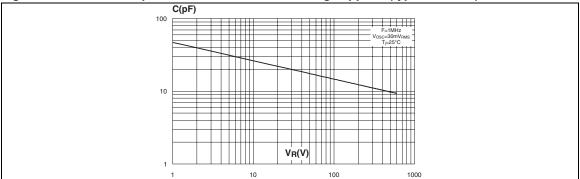


Figure 7. Junction capacitance versus reverse voltage applied (typical values)



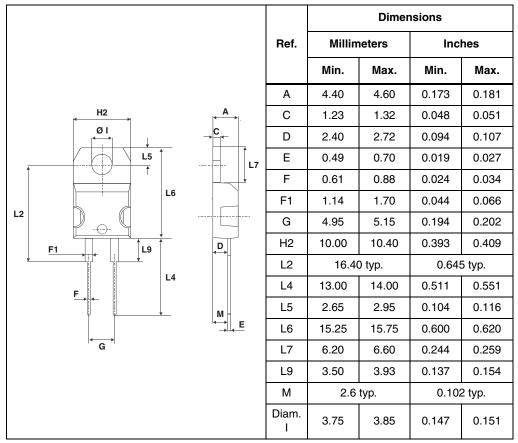
## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 to 0.6 N⋅m

In order to meet environmental requirements, ST (also) offers these devices in ECOPACK® packages. ECOPACK® packages are Lead-free. The category of second level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label.

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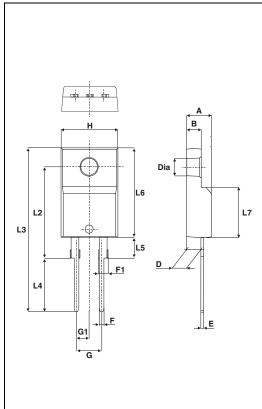
Table 6. TO-220AC dimensions



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Table 7. TO-220FPAC dimensions



	Dimensions				
Ref.	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
Α	4.4	4.6	0.173	0.181	
В	2.5	2.7	0.098	0.106	
D	2.5	2.75	0.098	0.108	
Е	0.45	0.70	0.018	0.027	
F	0.75	1	0.030	0.039	
F1	1.15	1.70	0.045	0.067	
G	4.95	5.20	0.195	0.205	
G1	2.4	2.7	0.094	0.106	
Н	10	10.4	0.393	0.409	
L2	16	Тур.	0.63	Тур.	
L3	28.6	30.6	1.126	1.205	
L4	9.8	10.6	0.386	0.417	
L5	2.9	3.6	0.114	0.142	
L6	15.9	16.4	0.626	0.646	
L7	9.00	9.30	0.354	0.366	
Dia.	3.00	3.20	0.118	0.126	

# 3 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH8S06D	STTH8S06D	TO-220AC	1.9 g	50	Tube
STTH8S06FP	STTH8S06FP	TO-220FPAC	1.64 g	50	Tube

# 4 Revision history

Table 9. Document revision history

Date	Revision	Description of changes
18-Dec-2007	1	First issue.

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